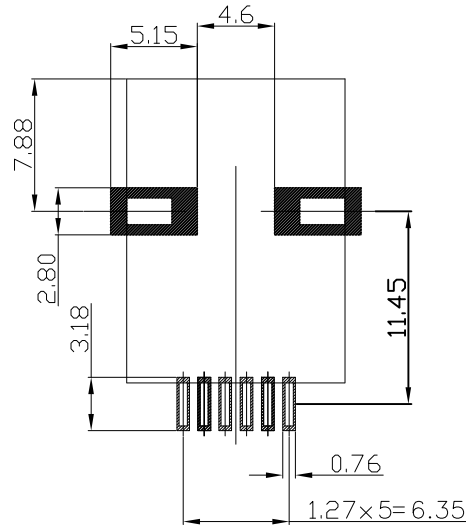
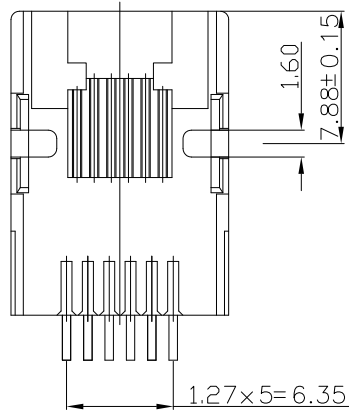
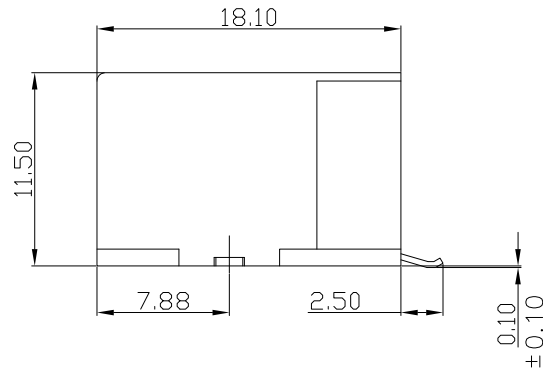
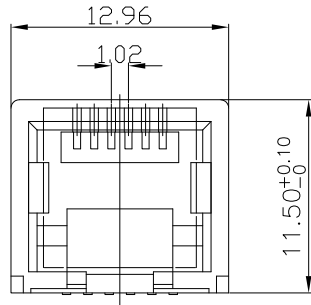


RoHS compliant



PCB LAYOUT/TOP VIEW

NOTES

MATERIAL

1. HOUSING MATERIAL : HIGH TEMP THERMOPLASTIC
FLAMMABILITY RATING UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE
3. PLATING : GOLD LATING OVER NICKEL IN CONTACT
TIN PLATING OVER NICKEL IN SOLDER AREA.
: FU", 3U", 6U", 15U", 30U", 50U".

ELECTRICAL

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 40 MILLIOHMS MAX.
4. INSULATION RESISTANCE : 1000 MEGOHMS MIN @ 500V DC .
5. DIELECTRIC STRENGTH : 1000V VAC RMS 60Hz. 1MIN.

MECHANICAL

1. DURRABILITY : 750 CYCLES MIN.
2. PCB RETENTIONPRE-SOLDER : 1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40℃~+85℃.
 2. OPERATION : -40℃~+85℃.
 3. IR Reflow Soldering Temperature:255℃ TO 265℃.
- Mates With Modular Plug Conforming TO FCC Part 68.Subpart F.

P/N:RJ56S-6611-010551X

56S RJ12 90° SMT SERIES PCB JACK
POSITIONS (金針位置):
6-6POSITIONS (6P)
CONTACTS (金針根數)
6-6CONTACTS (6C)
PORTS (端口):
11-1X1
SHIELD (屏蔽壳):
0-Without SHIELD (无屏蔽壳)
IRON PEG (铁脚定位脚):
1-PEG Inward (定位脚向内)
HOUSING PEG (塑胶定位柱)
1-Mushroom Feet (香菇脚)

PACKING TYPE (包装):
1-REEL (卷带包装)
2-PVC TRAY (盘装)
COLOR (颜色):
1-BLACK (黑色)
7-BLUE (蓝色)
PLASTIC (塑料):
4-LCP; 5-PA9T
GOLD PLATING (鍍金厚度):
1-1U"; 5-6U"; 10-15U"
7-30U"; 8-50U";

GENERAL TOLERANCE

.X	±0.35	X.°	± 2°
.XX	±0.25	.X°	± 1°
.XXX	±0.15	.XX°	± 0.5°

PROJECT

DRAWN

Gene Li

2019/06/15

CHECKE

JH

APPROVE

UNIT mm

SCALE

1:1

SHEET

1/1

X-SHUN 东莞市祥舜电子科技有限公司
DONGGUAN X-SHUN ELECTRONIC TECHNOLOGY CO., LTD

PART NO. RJ56S-6611-010551X

TITLE: RJ12 6P6C 90° SMT L=18.1MM PCB JACK

REV

A0

DRAWING NO.

RJ56S-66

REV

ECN NO

DESCRIPTION

DATE

SIGNATURE

A0

NEW DESIGN

2019/06/15

A

A